

CPW5-1200-Z050BSilicon Carbide Schottky Diode Chip

Z-Rec® Rectifier

 $V_{RRM} = 1200 \text{ V}$

 $I_{E} = 50 A$

 $Q_c = 246 \text{ nC}$

Features Chip Outline

- 1200-Volt Schottky Rectifier
- Zero Reverse Recovery
- Zero Forward Recovery
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on V_F



| Part Number | Die Size | Anode | Cathode |
|-----------------|---------------------------|-------|---------|
| CPW5-1200-Z050B | 4.9 x 4.9 mm ² | Al | Ni/Ag |

Maximum Ratings

| Symbol | Parameter | Value | Unit | Test Conditions | Note |
|-----------------------------------|--|----------------|------|-----------------------|------|
| V _{RRM} | Repetitive Peak Reverse Voltage | 1200 | V | | |
| V _{RSM} | Surge Peak Reverse Voltage | 1200 | V | | |
| V _R | DC Peak Blocking Voltage | 1300 | V | | |
| I _F | Continuous Forward Current | 50 | А | T _j =175°C | 1 |
| T _J , T _{stg} | Operating Junction and Storage Temperature | -55 to +175 | °C | | |
| T _{Proc} | Maximum Processing Temperature | 325 | °C | 10 min Maximum | |

Note:

1. Assumes $R_{\theta JC}$ Thermal Resistance < 0.25°C/W and T_{C} = 145 °C



Electrical Characteristics

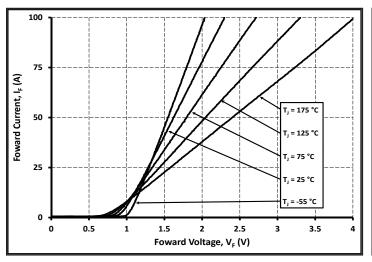
| Symbol | Parameter | Тур. | Max. | Unit | Test Conditions | Note |
|--------------------------------|-------------------------|--------------------|------|------|--|-------|
| V _F [| DC Forward Voltage | 1.6 1.25 | 1.8 | V | $I_F = 50 \text{ A } T_J = 25^{\circ}\text{C}$ $I_F = 25 \text{ A } T_J = 25^{\circ}\text{C}$ | Fig 1 |
| | | 2.25 1.55 | 2.7 | | I _F = 50 A T _J =175°C I _F = 25 A T _J =175°C | |
| I _R Reverse Current | Daviera Current | 100 6 | 500 | | $V_R = 1200 \text{ V } T_J = 25^{\circ}\text{C}$ $V_R = 800 \text{ V } T_J = 25^{\circ}\text{C}$ | Fig 2 |
| | Reverse Current | 300 40 | 1000 | μA | V _R = 1200 V T _J =175°C V _R = 800 V T _J =175°C | Fig 2 |
| Q _c | Total Capacitive Charge | 246 | | nC | V _R = 800 V, T _J = 25°C | Fig 4 |
| С | Total Capacitance | 3380 230 173 | | pF | $V_R = 0 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ $V_R = 400 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ $V_R = 800 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ | Fig 3 |

Mechanical Parameters

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|------------------------------|-----------|------|--|--|--|
| Parameter | Тур. | Unit | | | |
| Die Size | 4.9 x 4.9 | mm | | | |
| Anode Pad opening | 3.8 x 3.8 | mm | | | |
| Thickness | 380 ± 10% | μm | | | |
| Wafer Size | 100 | mm | | | |
| Anode Metalization (AI) | 4 | μm | | | |
| Cathode Metalization (Ni/Ag) | 1.8 | μm | | | |
| Frontside Passivation | Polyimide | | | | |



Typical Performance



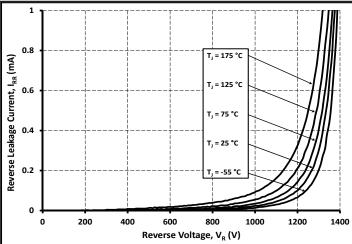
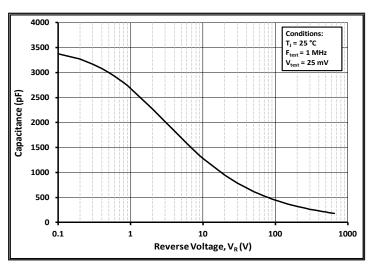


Figure 1. Typical Forward Characteristics





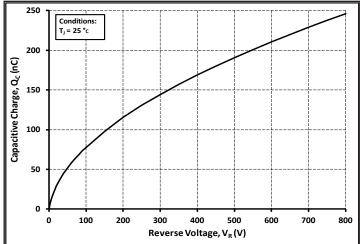
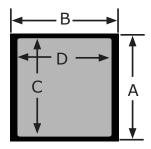


Figure 3. Typical Capacitance vs. Reverse Voltage

Figure 4. Typical Recovery Charge vs. Reverse Voltage



Chip Dimensions



| symbol | dimension | | |
|--------|-----------|-------|--|
| | mm | inch | |
| Α | 4.9 | 0.193 | |
| В | 4.9 | 0.193 | |
| С | 3.8 | 0.150 | |
| D | 3.8 | 0.150 | |

Notes

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

This product has not been designed or tested for use in, and is not intended for use in, applications implanted into
the human body nor in applications in which failure of the product could lead to death, personal injury or property
damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines,
cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control
systems, or air traffic control systems.

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